

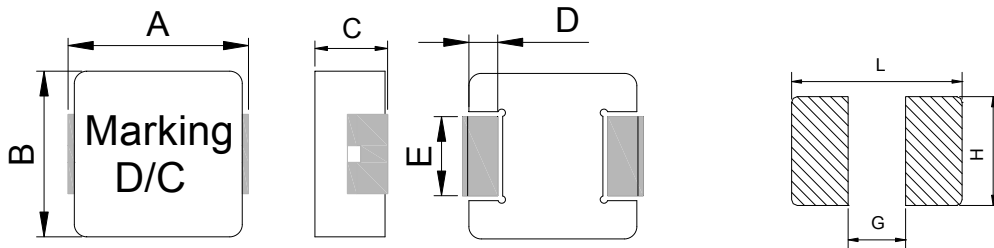
## 1. Part No. Expression:

**PIAQ0502SP1R0MN**

(a)      (b)      (c)      (d)      (e)

- a) Series Code
- b) Dimension Code
- c) Type Code
- d) Inductance Code
- e) Tolerance Code

## 2. Configuration & Dimensions:



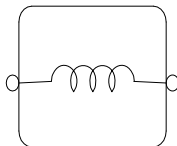
- Note:
1. The above PCB layout is for reference only.
  2. Solder paste thickness of 0.12mm and above is recommended.
  3. Marking: Top row – Inductance code, Bottom row – YYWW.

Recommended PC Board Pattern

Unit: mm

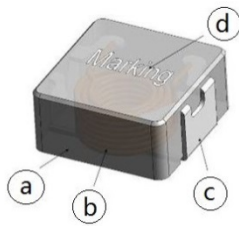
A	B	C	D	E	L	G	H
5.7±0.3	5.2±0.2	1.8±0.2	1.0±0.3	2.5±0.3	6.0 Ref.	2.8 Ref.	2.5 Ref.

## 3. Schematic:



NOTE: Specifications subject to change without notice. Please check our website for latest information.

## 4. Material List:



- a) Core
- b) Wire
- c) Terminal
- d) Ink

## 5. General Specification:

- (a) Reliability test for this part meets AEC-Q200 standard.
- (b) Operating Temp. : -55°C to +155°C (Including self - temperature rise).
- (c) Storage Temp. : -55°C to +155°C (on board).
- (d) Humidity Range. : 85 ± 3% RH.
- (e) Heat Rated Current (Irms) will cause the coil temperature rise approximately  $\Delta T$  of 40°C.
- (f) Saturation Current (Isat) will cause L0 to drop approximately 30%.
- (g) Part Temp. (Ambient+Temp. Rise) should not exceed 155°C under worst case operating conditions.
- (h) Storage condition (component in its packaging)
  - i) Temperature: Less than 40°C
  - ii) Humidity : 60% RH

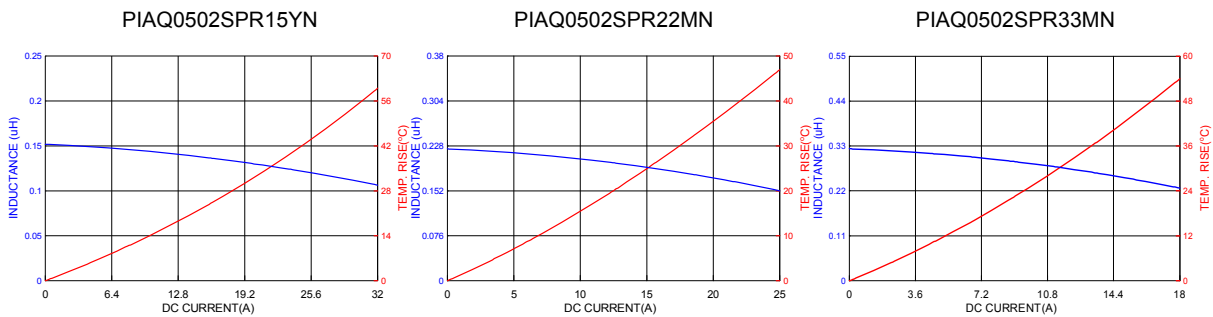
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6. Electrical Characteristics:

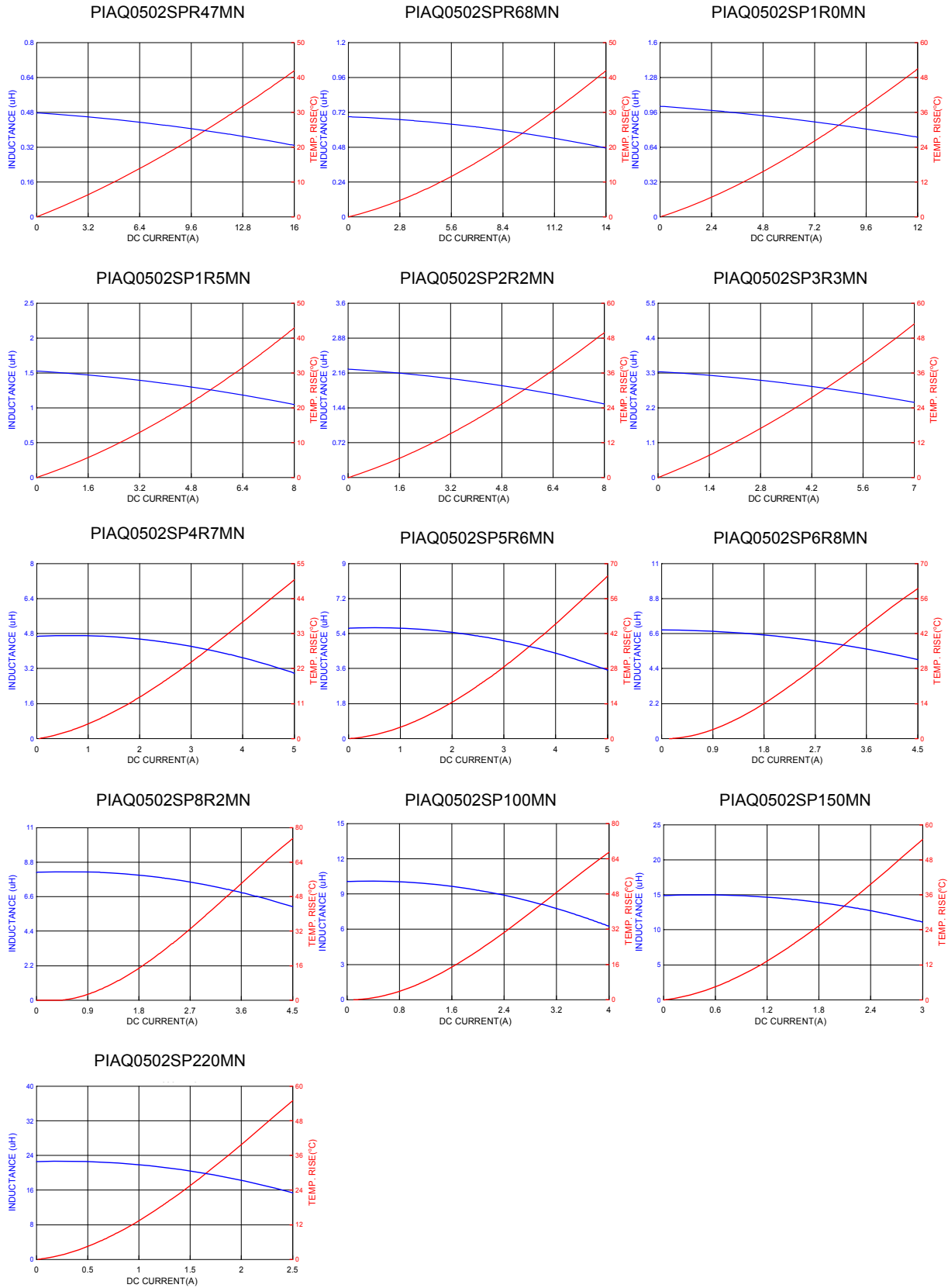
Part Number	Inductance L (uH) @ 0A	Test Frequency (Hz)	I <sub>rms</sub> (A) Typ.	I <sub>rms</sub> (A) Max.	I <sub>sat</sub> (A) Typ.	I <sub>sat</sub> (A) Max.	DCR (mΩ) Typ.	DCR (mΩ) Max.
PIAQ0502SPR15YN	0.15	1.0V/100K	22.0	19.0	27.0	24.0	2.8	3.2
PIAQ0502SPR22MN	0.22	1.0V/100K	16.0	14.0	20.0	17.0	3.8	4.4
PIAQ0502SPR33MN	0.33	1.0V/100K	14.0	13.0	11.0	9.0	5.2	6.0
PIAQ0502SPR47MN	0.47	1.0V/100K	13.0	11.0	9.0	8.0	6.1	7.2
PIAQ0502SPR68MN	0.68	1.0V/100K	12.0	10.0	8.0	7.0	8.0	9.2
PIAQ0502SP1R0MN	1.00	1.0V/100K	8.6	7.5	7.5	6.5	14.0	16.2
PIAQ0502SP1R5MN	1.50	1.0V/100K	7.5	6.5	7.0	6.0	22.0	26.4
PIAQ0502SP2R2MN	2.20	1.0V/100K	6.5	6.0	5.8	5.0	29.0	34.0
PIAQ0502SP3R3MN	3.30	1.0V/100K	6.0	5.0	5.0	4.7	50.0	60.0
PIAQ0502SP4R7MN	4.70	1.0V/100K	4.0	3.0	4.7	4.4	84.0	97.0
PIAQ0502SP5R6MN	5.60	1.0V/100K	3.5	2.8	4.4	4.0	91.0	109
PIAQ0502SP6R8MN	6.80	1.0V/100K	3.1	2.6	4.2	3.8	110	127
PIAQ0502SP8R2MN	8.20	1.0V/100K	2.9	2.5	3.9	3.4	123	142
PIAQ0502SP100MN	10.0	1.0V/100K	2.7	2.4	3.5	3.0	150	180
PIAQ0502SP150MN	15.0	1.0V/100K	2.2	1.9	2.6	2.3	224	252
PIAQ0502SP220MN	22.0	1.0V/100K	1.9	1.6	2.2	1.9	290	325

\*Tolerance code: M = ±20%, Y= ±30%

7. Characteristics Curves:



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**8. Soldering:**

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. Our terminations are suitable for all-re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air.

**8-1 Solder Re-flow**

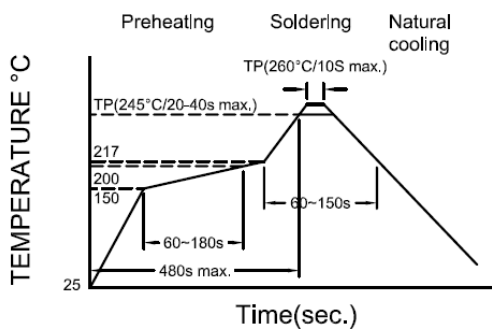
Recommended temperature profiles for re-flow soldering in Figure 1.

**8-2 Soldering Iron (Figure 2)**

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

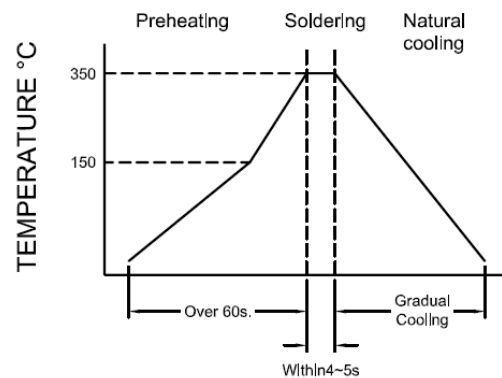
Note:

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 secs.



Reflow times: 3 times max

Fig.1



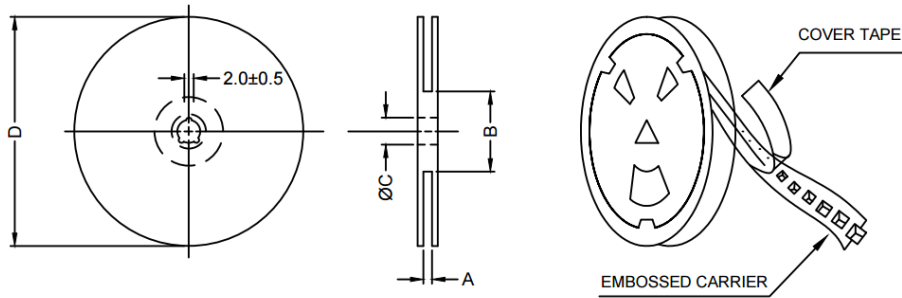
Iron Soldering times: 1 times max

Fig.2

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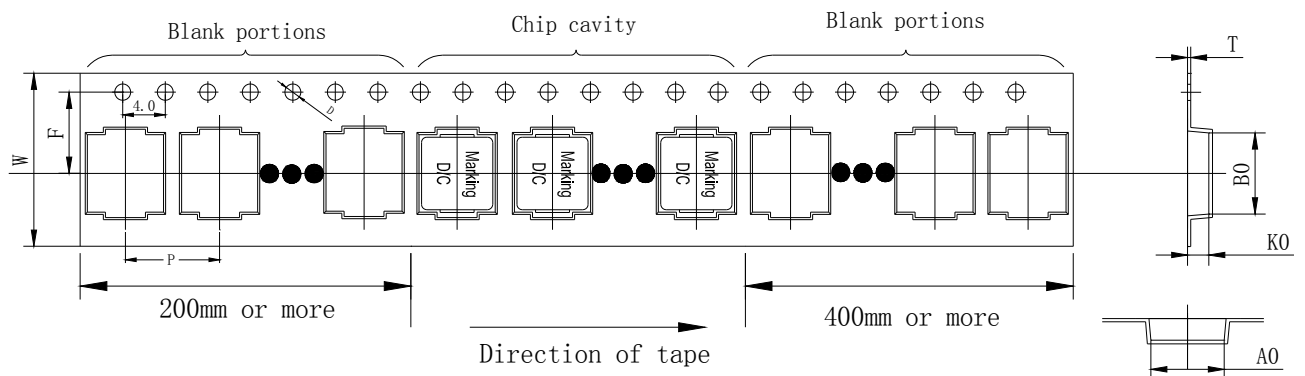
9. Packaging Information:

9-1 Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x12mm	12.4+2/-0	100±2	13+0.5/-0.2	330

9-2 Tape Dimension



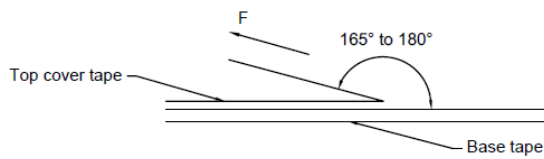
Series	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	T(mm)	D(mm)
PIAQ	0502	6.2±0.1	5.6±0.1	2.3±0.1	8.0±0.1	12.0±0.3	5.5±0.1	0.35±0.05	1.5±0.1

9-3 Packaging Quantity

PIAQ	0502
Chip / Reel	3000
Inner box	6000
Carton	24000

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## 9-4 Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

## Application Notice:

### 1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- Recommended products should be used within 12 months from the time of delivery.
- The packaging material should be kept where no chlorine or sulfur exists in the air.

### 2. Transportation:

- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Vacuum pick up is strongly recommended for individual components.
- Bulk handling should ensure that abrasion and mechanical shock are minimized.

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